

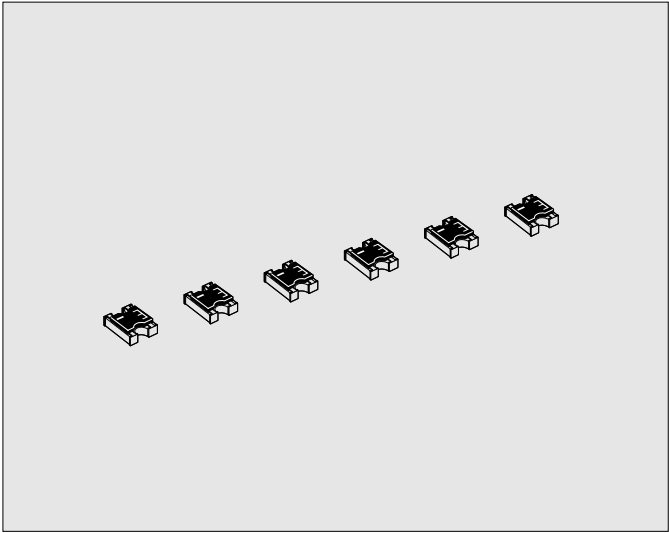
CHIP ATTENUATORS

KAMAYA OHM

RAC101A

●Features

- 1. Suitable for use at DC and up to UHF band frequencies.
- 2. Replaceable three discrete resistors with one chip on attenuation circuits.
- 3. Please contact KAMAYA for Halogen and Antimony free product of RAC101A.



●Dimensions and Circuits

Dot mark on Termination 1  
Attenuation factor on Termination 2 to 3

Circuits

Unbalanced  $\pi$  Type

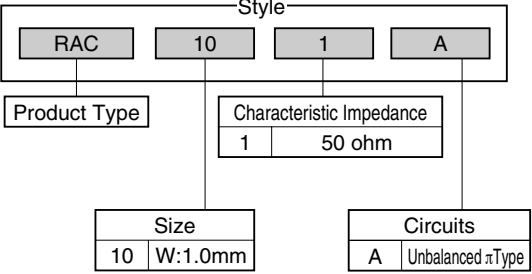
Style	Terminal Style	L	W	H	Q	a	b	*P	*Unit weight/pc.
RAC101A	C	1.0±0.05	1.0±0.05	0.35±0.05	0.33±0.10	0.15±0.10	0.25 <sup>+0.05</sup> <sub>-0.10</sub>	0.65	1.1mg

Unit : mm

\*Values for reference

●Part Number Description

Example



1	C	TH
Attenuation Factor		* Packaging & Standard Qty. (Min.)
0		B Bulk (Loose Package) 1,000pcs.
X		TH Paper Tape (2 mm pitch) 10,000pcs.
1		*Refer to Tape and Packaging information on pages 54 and 55.
Y		
2		
3		
4		
5		
6		
7		
8		
9		
A		
B		
C		
D		
E		
F		
G		
H		
J		
K		
L		
	Terminal Style	
	C Convex Type With corner	

## CHIP ATTENUATORS

## RAC101A

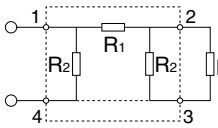
## ●Ratings

Style	Characteristic Impedance	Attenuation Factor		Tolerance on Attenuation Factor dB	Voltage Standing Wave Ratio	Frequency Range	Rated Input Power mW/package	Category Temperature Range °C
		symbol	dB					
RAC101A	-	0	0	-	-	-	100	-40~+125
	50 ohm	X	0.5	±0.1	1.1max.	DC ≤f ≤3GHz		
		1	1	±0.3	1.2max.			
		Y	1.5					
		2	2					
		3	3					
		4	4					
		5	5					
		6	6	±0.4				
		7	7					
		8	8					
		9	9					
		A	10	±0.8				
		B	11					
		C	12					
		D	13	±1.0				
		E	14	±1.5				
		F	15					
		G	16	±2.0				
		H	17					
		J	18					
	K	19						
	L	20	±2.5					

Note. The following information is available.

1. Test methods for Attenuation Factor and VSWR characteristics.

## ●Performance Characteristics JIS C 5201-1 : 1998

Description	Requirements			Test Methods
	0.5~2dB	3dB~5dB	6dB~20dB	
Characteristic impedance	50 ohm			Measuring Circuits  RL=50 ohm
Insulation resistance	At least 100M ohm			50Vd.c., 60s
Solderability	In accordance with Clause 4.17.4.5			Clause 4.17 Dip into 235°C Solder bath for 2s.
Resistance to soldering heat	Within ±0.1dB No major visible damage.	Within ±0.2dB	Within ±0.3dB	Clause 4.18 Dip into 260°C Solder bath for 5s.
Rapid change of temperature	Within ±0.1dB No major visible damage.	Within ±0.2dB	Within ±0.3dB	Clause 4.19 5 cycles between -55°C and +125°C.
Endurance at 85°C	Within ±0.1dB	Within ±0.2dB	Within ±0.3dB	Clause 4.25.1 Rated input power, 1.5h"ON", 0.5h"OFF", 85°C, 1,000h.
Bend strength of the face plating	Within ±0.1dB	Within ±0.2dB	Within ±0.3dB	Clause 4.33 Amount of bend : 3 mm